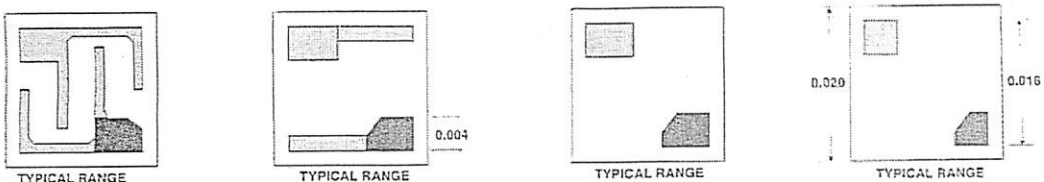
Eastern States Components, Inc.

108 Pratts Junction Road / Sterling, MA 01564

P) 978.422.7641 F) 978.422.6762

Series:	WBCR
Manufacturer:	EFI
Nominal Dimensions:	.020 x .020 +/- .002 x .010 +/- .003
Top Side Metallization:	AL
Back Side Metallization:	AU

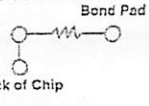
DIMENSIONS in inches



TYPICAL RANGE 10 - 23 | TYPICAL RANGE 24 - 220 | TYPICAL RANGE 180 - 2.2K | TYPICAL RANGE 1.6K - 1M

NOTE: Notched Shaded area represents Top Bonding Pad. The backside of the chip constitutes the Second Resistor Connection.

SCHEMATIC



MECHANICAL SPECIFICATIONS in inches	
PARAMETER	
Chip size	0.020 x 0.020 ± 0.002 (0.50 x 0.50 ± 0.05mm)
Chip thickness	0.010 ± 0.003 (0.253 ± 0.05mm)
Chip substrate material	Oxidized silicon, 10kÅ minimum SiO_2
Resistor material	Tantalum nitride, self-passivating
Bonding pad size	0.004 x 0.004 (0.100 x 0.100mm)
Number of pads	1
Pad material	10kÅ minimum aluminum
Backing	3kÅ minimum gold
Recommended attachment method	Eutectic or conductive epoxy

OPTION: Gold bonding pads, 15kÅ minimum thickness.
Consult Applications Engineer

ORDERING INFORMATION

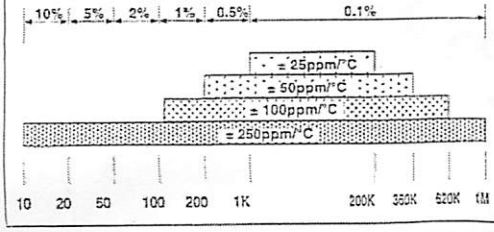
Example: 100% visualled, 16k , ± 1%, ± 250ppm/°C TCR, Aluminum Pads, Class H

P/N:

W	BCR	008	1600	1	F
INSPECTION /PACKAGING	PRODUCT FAMILY	PROCESS CODE	RESISTANCE VALUE	MULTIPLIER CODE	TOLERANCE CODE
W = 100% visually inspected parts in matrix trays per MIL-STD-883 X = Sample, visually inspected loaded in matrix trays (4% AQL)		See Process Code table	Use first 4 significant digits of resistance	B = 0.01 A = 0.1 0 = 1 1 = 10 2 = 100 3 = 1000	B = 0.1% C = 0.2% D = 0.5% F = 1.0% G = 2.0% H = 2.5% J = 5.0% K = 10% M = 20% L = 25% N = 50%

TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES AND TOLERANCES

Tightest Standard Tolerance Available



PROCESS CODE	
CLASS H*	CLASS K*
010	055
002	051
027	059
008	052

*MIL-PRF-38534